TEXAS INSTRUMENTS
DLPC1438
DLPS217 – JULY 2021

DLPC1438 Digital Controller for DLP 3D Printers

1 Features

- Digital Controller for DLP300S and DLP301S 0.3-inch 3.6-Megapixel DMDs
- 3D Printing Features:
  - Linear gamma modes optimized for optimizing illumination uniformity and greyscale printing
  - Programmable layer exposure time
  - 8-bit greyscale output
- System Features:
  - Front-end FPGA with low-cost SPI data input interface
  - Actuator control
  - Programmable LED current control
- Operation optimized for reliable performance in DLP 3D printer applications
- Pair with DLPA2000, DLPA2005, DLPA3000, or DLPA3005 PMIC (power management integrated circuit) and LED driver

2 Applications

- TI DLP® 3D Printer
  - Additive manufacturing
  - Vat polymerization
  - Masked stereolithography (mSLA 3D printer)
- Dental DLP 3D printer
- Light exposure: programmable spatial and temporal light exposure

3 Description

The DLPC1438 3D print controller supports reliable operation of the DLP300S and DLP301S digital micromirror devices (DMDs) for DLP 3D Printer applications. The DLPC1438 controller provides a convenient interface between user electronics and the DMD to enable fast, high resolution, reliable DLP 3D printers.

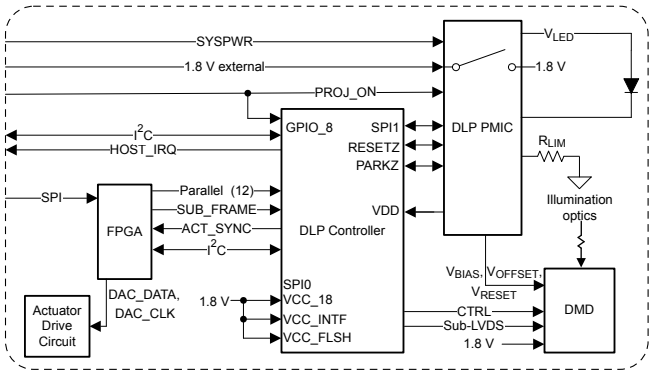
Get started with TI DLP® light-control technology page to learn how to get started with the DLP300S.

The DLP advanced light control resources on ti.com accelerate time to market, which include reference designs, optical modules manufactures, and DLP design network partners.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DLPC1438	NFBGA (201)	13.00 mm × 13.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Application

ADVANCE INFORMATION

Table of Contents

4 Revision History

DATE	REVISION	NOTES
July 2021	*	Initial Release

ADVANCE INFORMATION

5 Pin Configuration and Functions

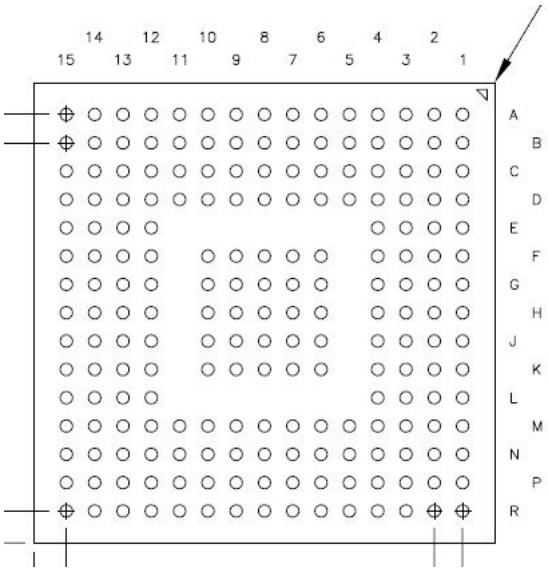


Figure 5-1. ZEZ Package 201-Pin NFBGA Bottom View

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
A	DMD_LS_CLK	DMD_LS_WDATA	DMD_HS_WDATAH_P	DMD_HS_WDATAG_P	DMD_HS_WDATAF_P	DMD_HS_WDATAE_P	DMD_HS_CLK_P	DMD_HS_WDATAD_P	DMD_HS_WDATAC_P	DMD_HS_WDATAB_P	DMD_HS_WDATAA_P	CMP_OUT	SPI0_CLK	SPI0_CSZ0	CMP_PWM
B	DMD_DEN_ARSTZ	DMD_LS_RDATA	DMD_HS_WDATAH_N	DMD_HS_WDATAG_N	DMD_HS_WDATAF_N	DMD_HS_WDATAE_N	DMD_HS_CLK_N	DMD_HS_WDATAD_N	DMD_HS_WDATAC_N	DMD_HS_WDATAB_N	DMD_HS_WDATAA_N	SPI0_DIN	SPI0_DOUT	LED_SEL_1	LED_SEL_0
C	DD3P	DD3N	VDDLP12	VSS	VDD	VSS	VCC	VSS	VCC	HWTEST_EN	RESETZ	SPI0_CSZ1	PARKZ	GPIO_00	GPIO_01
D	DD2P	DD2N	VDD	VCC	VDD	VSS	VDD	VSS	VDD	VSS	VCC_FLSH	VDD	VDD	GPIO_02	GPIO_03
E	DCLKP	DCLKN	VDD	VSS								VCC	VSS	GPIO_04	GPIO_05
F	DD1P	DD1N	RREF	VSS		VSS	VSS	VSS	VSS	VSS		VCC	VDD	GPIO_06	GPIO_07
G	DD0P	DD0N	VSS_PLLM	VSS		VSS	VSS	VSS	VSS	VSS		VSS	VSS	GPIO_08	GPIO_09
H	PLL_REFCLK_I	VDD_PLLM	VSS_PLLD	VSS		VSS	VSS	VSS	VSS	VSS		VSS	VDD	GPIO_10	GPIO_11
J	PLL_REFCLK_O	VDD_PLLD	VSS	VDD		VSS	VSS	VSS	VSS	VSS		VDD	VSS	GPIO_12	GPIO_13
K	PDATA_1	PDATA_0	VDD	VSS		VSS	VSS	VSS	VSS	VSS		VSS	VCC	GPIO_14	GPIO_15
L	PDATA_3	PDATA_2	VSS	VDD								VDD	VDD	GPIO_16	GPIO_17
M	PDATA_5	PDATA_4	VCC_INTF	VSS	VSS	VDD	VCC_INTF	VSS	VDD	VDD	VCC	VSS	JTAGTMS1	GPIO_18	GPIO_19
N	PDATA_7	PDATA_6	VCC_INTF	PDM_CVS_TE	HSYNC_CS	3DR	VCC_INTF	HOST_IRQ	IIC0_SDA	IIC0_SCL	JTAGTMS2	JTAGTDO2	JTAGTDO1	TSTPT_6	TSTPT_7
P	VSYNC_WE	DATEN_CMD	PCLK	PDATA_11	PDATA_13	PDATA_15	PDATA_17	PDATA_19	PDATA_21	PDATA_23	JTAGTRSTZ	JTAGTCK	JTAGTDI	TSTPT_4	TSTPT_5
R	PDATA_8	PDATA_9	PDATA_10	PDATA_12	PDATA_14	PDATA_16	PDATA_18	PDATA_20	PDATA_22	IIC1_SDA	IIC1_SCL	TSTPT_0	TSTPT_1	TSTPT_2	TSTPT_3

ADVANCE INFORMATION

Table 5-1. Test Pins and General Control

PIN		I/O	TYPE[4]	DESCRIPTION
NAME	NO.			
HWTEST_EN	C10	I	6	Manufacturing test enable signal. Connect this signal directly to ground on the PCB for normal operation.
PARKZ	C13	I	6	DMD fast park control (active low Input with a hysteresis buffer). This signal is used to quickly park the DMD when loss of power is imminent. The longest lifetime of the DMD may not be achieved with the fast park operation; therefore, this signal is intended to only be asserted when a normal park operation is unable to be completed. The PARKZ signal is typically provided from the DLPAxxxx interrupt output signal.
JTAGTCK	P12	I	6	TI internal use. Leave this pin unconnected.
JTAGTDI	P13	I	6	TI internal use. Leave this pin unconnected.
JTAGTDO1	N13[1]	O	1	TI internal use. Leave this pin unconnected.
JTAGTDO2	N12[1]	O	1	TI internal use. Leave this pin unconnected.
JTAGTMS1	M13	I	6	TI internal use. Leave this pin unconnected.
JTAGTMS2	N11	I	6	TI internal use. Leave this pin unconnected.
JTAGTRSTZ	P11	I	6	TI internal use. This pin must be tied to ground, through an external resistor for normal operation. Failure to tie this pin low during normal operation can cause start up and initialization problems.[2]
RESETZ	C11	I	6	Power-on reset (active low input with a hysteresis buffer). Self-configuration starts when a low-to-high transition is detected on RESETZ. All controller power and clocks must be stable before this reset is de-asserted. No signals are in their active state while RESETZ is asserted. This pin is typically connected to the RESETZ pin of the DLPA200x or RESET_Z of the DLPA300X.
TSTPT_0	R12	I/O	1	Test pins (includes weak internal pulldown). Pins are tri-stated while RESETZ is asserted low. Sampled as an input test mode selection control approximately 1.5 µs after de-assertion of RESETZ, and then driven as outputs.[2] [3] Normal use: reserved for test output. Leave open for normal use. Note: An external pullup may put the DLPC1438 in a test mode.
TSTPT_1	R13	I/O	1	
TSTPT_2	R14	I/O	1	
TSTPT_3	R15	I/O	1	
TSTPT_4	P14	I/O	1	Test pin 4 (Includes weak internal pulldown) – tri-stated while RESETZ is asserted low. Sampled as an input test mode selection control approximately 1.5 µs after de-assertion of RESETZ and then driven as an output.
TSTPT_5	P15	I/O	1	Test pins (includes weak internal pulldown). Pins are tri-stated while RESETZ is asserted low. Sampled as an input test mode selection control approximately 1.5 µs after de-assertion of RESETZ, and then driven as outputs.[2] [3] Normal use: reserved for test output. Leave open for normal use. Note: An external pullup may put the DLPC1438 in a test mode.
TSTPT_6	N14	I/O	1	
TSTPT_7	N15	I/O	1	

(1) If the application design does not require an external pullup, and there is no external logic that can overcome the weak internal pulldown resistor, then this I/O pin can be left open or unconnected for normal operation. If the application design does not require an external pullup, but there is external logic that might overcome the weak internal pulldown resistor, then an external pulldown is recommended to ensure a logic low.
(2) External resistor must have a value of 8 kΩ or less to compensate for pins that provide internal pullup or pulldown resistors.
(3) If the application design does not require an external pullup and there is no external logic that can overcome the weak internal pulldown, then the TSTPT I/O can be left open (unconnected) for normal operation. If operation does not call for an external pullup, but there is external logic that might overcome the weak internal pulldown resistor, then an external pulldown resistor is recommended to ensure a logic low.
(4) See Table 5-10 for type definitions.

Table 5-2. Parallel Port Input

PIN[1]		I/O	TYPE[3]	DESCRIPTION
NAME	NO.			
PCLK	P3	I	11	Pixel clock
PDM_CVS_TE	N4	I/O	5	Parallel data mask. Programable polarity with default of active high. Optional signal.

Table 5-2. Parallel Port Input (continued)

PIN[1]		I/O	TYPE[3]	DESCRIPTION
NAME	NO.			
VSYNC_WE	P1	I	11	Vsync[2]
HSYNC_CS	N5	I	11	Hsync[2]
DATAEN_CMD	P2	I	11	Data valid
PDATA_0 PDATA_1 PDATA_2 PDATA_3 PDATA_4 PDATA_5 PDATA_6 PDATA_7	K2 K1 L2 L1 M2 M1 N2 N1	I	11	(bit weight 1) (bit weight 2) (bit weight 4) (bit weight 8) (bit weight 16) (bit weight 32) (bit weight 64) (bit weight 128)
PDATA_8 PDATA_9 PDATA_10 PDATA_11 PDATA_12 PDATA_13 PDATA_14 PDATA_15	R1 R2 R3 P4 R4 P5 R5 P6	I	11	Unused
PDATA_16 PDATA_17 PDATA_18 PDATA_19 PDATA_20 PDATA_21 PDATA_22 PDATA_23	R6 P7 R7 P8 R8 P9 R9 P10	I	11	Unused
3DR	N6	I	11	Unused

(1) Connect unused inputs to ground or pulldown to ground through an external resistor (8 kΩ or less).
(2) VSYNC and HSYNC polarity can be adjusted by software.
(3) See Table 5-10 for type definitions.

ADVANCE INFORMATION

Table 5-3. DSI Input Data and Clock

PIN		I/O	Type(1)	DESCRIPTION
NAME	NO.			
DCLKN DCLKP	E2 E1	---	---	unused; Leave unconnected and floating.
DD0N DD0P DD1N DD1P DD2N DD2P DD3N DD3P	G2 G1 F2 F1 D2 D1 C2 C1	---	---	unused; Leave unconnected and floating.
RREF	F3	—	---	Leave this pin unconnected and floating.

(1) See Table 5-10 for type definitions.

Table 5-4. DMD Reset and Bias Control

PIN		I/O	TYPE(1)	DESCRIPTION
NAME	NO.			
DMD_DEN_ARSTZ	B1	O	2	DMD driver enable (active high). DMD reset (active low). When corresponding I/O power is supplied, the controller drives this signal low after the DMD is parked and before power is removed from the DMD. If the 1.8-V power to the DLPC1438 is independent of the 1.8-V power to the DMD, then TI recommends including a weak, external pulldown resistor to hold the signal low in case DLPC1438 power is inactive while DMD power is applied.
DMD_LS_CLK	A1	O	3	DMD, low speed (LS) interface clock
DMD_LS_WDATA	A2	O	3	DMD, low speed (LS) serial write data
DMD_LS_RDATA	B2	I	6	DMD, low speed (LS) serial read data

(1) See Table 5-10 for type definitions.

Table 5-5. DMD Sub-LVDS Interface

PIN		I/O	TYPE(1)	DESCRIPTION
NAME	NO.			
DMD_HS_CLK_P DMD_HS_CLK_N	A7 B7	O	4	DMD high speed (HS) interface clock
DMD_HS_WDATA_H_P DMD_HS_WDATA_H_N DMD_HS_WDATA_G_P DMD_HS_WDATA_G_N DMD_HS_WDATA_F_P DMD_HS_WDATA_F_N DMD_HS_WDATA_E_P DMD_HS_WDATA_E_N DMD_HS_WDATA_D_P DMD_HS_WDATA_D_N DMD_HS_WDATA_C_P DMD_HS_WDATA_C_N DMD_HS_WDATA_B_P DMD_HS_WDATA_B_N DMD_HS_WDATA_A_P DMD_HS_WDATA_A_N	A3 B3 A4 B4 A5 B5 A6 B6 A8 B8 A9 B9 A10 B10 A11 B11	O	4	DMD sub-LVDS high speed (HS) interface write data lanes. The true numbering and application of the DMD_HS_WDATA pins depend on the software configuration.

(1) See Table 5-10 for type definitions.

Table 5-6. Peripheral Interface(1)

PIN(1)		I/O	TYPE(2)	DESCRIPTION
NAME	NO.			
CMP_OUT	A12	I	6	Successive approximation ADC (analog-to-digital converter) comparator output (DLPC1438 Input). To implement, use a successive approximation ADC with a thermistor feeding one input of the external comparator and the DLPC1438 controller GPIO_10 (RC_CHARGE) pin driving the other side of the comparator. It is recommended to use the DLPAxxxx to achieve this function. CMP_OUT must be pulled-down to ground if this function is not used. (hysteresis buffer)
CMP_PWM	A15	O	1	TI internal use. Leave this pin unconnected.
HOST_IRQ	N8	O	9	Host interrupt (output) HOST_IRQ indicates when the DLPC1438 auto-initialization is in progress and most importantly when it completes. This pin is tri-stated during reset. An external pullup must be included on this signal.
IIC0_SCL(3)	N10	I/O	7	I^2C slave (port 0) SCL (bidirectional, open-drain signal with input hysteresis): This pin requires an external pullup resistor. The slave I^2C I/Os are 3.6-V tolerant (high-voltage-input tolerant) and are powered by VCC_INTF (which can be 1.8, 2.5, or 3.3 V). External I^2C pullups must be connected to a host supply with an equal or higher supply voltage, up to a maximum of 3.6 V (a lower pullup supply voltage does not typically satisfy the V_{IH} specification of the slave I^2C input buffers).
IIC1_SCL	R11	I/O	8	TI internal use. TI recommends an external pullup resistor.
IIC0_SDA(3)	N9	I/O	7	I^2C slave (port 0) SDA. (bidirectional, open-drain signal with input hysteresis): This pin requires an external pullup resistor. The slave I^2C port is the control port of controller. The slave I^2C I/O pins are 3.6-V tolerant (high-volt-input tolerant) and are powered by VCC_INTF (which can be 1.8, 2.5, or 3.3 V). External I^2C pullups must be connected to a host supply with an equal or higher supply voltage, up to a maximum of 3.6 V (a lower pullup supply voltage does not typically satisfy the V_{IH} specification of the slave I^2C input buffers).
IIC1_SDA	R10	I/O	8	TI internal use. TI recommends an external pullup resistor.
LED_SEL_0	B15	O	1	LED enable select. Automatically controlled by the DLPC1438 programmable DMD sequence LED_SEL(1:0) — Enabled LED 00 — None 01 — Red 10 — Green 11 — Blue
LED_SEL_1	B14	O	1	The controller drives these signals low when RESETZ is asserted and the corresponding I/O power is supplied. The controller continues to drive these signals low throughout the auto-initialization process. A weak, external pulldown resistor is recommended to ensure that the LEDs are disabled when I/O power is not applied.
SPI0_CLK	A13	O	13	SPI (Serial Peripheral Interface) port 0, clock. This pin is typically connected to the flash memory clock.
SPI0_CSZ0	A14	O	13	SPI port 0, chip select 0 (active low output). This pin is typically connected to the flash memory chip select. TI recommends an external pullup resistor to avoid floating inputs to the external SPI device during controller reset assertion.
SPI0_CSZ1	C12	O	13	SPI port 0, chip select 1 (active low output). This pin typically remains unused. TI recommends an external pullup resistor to avoid floating inputs to the external SPI device during controller reset assertion.
SPI0_DIN	B12	I	12	Synchronous serial port 0, receive data in. This pin is typically connected to the flash memory data out.
SPI0_DOUT	B13	O	13	Synchronous serial port 0, transmit data out. This pin is typically connected to the flash memory data in.

(1) External pullup resistor must be 8 kΩ or less.
(2) See Table 5-10 for type definitions.

ADVANCE INFORMATION

(3) When VCC_INTF is powered and VDD is not powered, the controller may drive the IIC0_xxx pins low which prevents communication on this I^2C bus. Do not power up the VCC_INTF pin before powering up the VDD pin for any system that has additional slave devices on this bus.

Table 5-7. GPIO Peripheral Interface(1)

PIN(1)		I/O	TYPE(3)	DESCRIPTION(2)
NAME	NO.			
GPIO_19	M15	I/O	1	General purpose I/O 19 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_18	M14	I/O	1	General purpose I/O 18 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_17	L15	I/O	1	General purpose I/O 17 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_16	L14	I/O	1	General purpose I/O 16 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_15	K15	I/O	1	General purpose I/O 15 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_14	K14	I/O	1	General purpose I/O 14 (hysteresis buffer). FPGA_RDY (input): Input from FPGA, indicating when the FPGA initialization process is complete.
GPIO_13	J15	I/O	1	General purpose I/O 13 (hysteresis buffer). AWG_ERR (input): Input from FPGA, indicating instability in actuator operation in order to halt printing and recover.
GPIO_12	J14	I/O	1	General purpose I/O 12 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_11	H15	I/O	1	General purpose I/O 11 (hysteresis buffer). Options: 1. Thermistor power enable (output). Turns on the power to the thermistor when it is used and enabled. 2. Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_10	H14	I/O	1	General Purpose I/O 10 (hysteresis buffer). Options: 1. RC_CHARGE (output): Intended to feed the RC charge circuit of the thermistor interface. 2. Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_09	G15	I/O	1	General purpose I/O 09 (hysteresis buffer). Reserved for Print Active signal. Indicates that a layer is actively being printed with previously sent print layer command. Applicable to External Print Mode only.
GPIO_08	G14	I/O	1	General purpose I/O 08 (hysteresis buffer). Normal mirror parking request (active low): To be driven by the PROJ_ON output of the host. A logic low on this signal causes the DLPC1438 to PARK the DMD, but it does not power down the DMD (the DLPAxxxx does that instead). The minimum high time is 200 ms. The minimum low time is 200 ms.
GPIO_07	F15	I/O	1	General purpose I/O 07 (hysteresis buffer). ACT_SYNC (output): Output to FPGA, used for synchronizing the actuator position with the controller data processing.
GPIO_06	F14	I/O	1	General purpose I/O 06 (hysteresis buffer). Reserved for System Ready signal (Output). Indicates when system is configured and ready for first print layer command after being commanded to go into External Print Mode. Applicable to External Print Mode only.
GPIO_05	E15	I/O	1	General purpose I/O 05 (hysteresis buffer). Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.

Table 5-7. GPIO Peripheral Interface(1) (continued)

PIN(1)		I/O	TYPE(3)	DESCRIPTION(2)
NAME	NO.			
GPIO_04	E14	I/O	1	General purpose I/O 04 (hysteresis buffer). Options: 1. SPI1_CSZ1 (active-low output): Optional SPI1 chip select 1 signal. Requires an external pullup resistor to deactivate this signal during reset and auto-initialization processes. 2. Optional GPIO. If unused TI recommends this pin be configured as a logic zero GPIO output and left unconnected. Otherwise this pin requires an external pullup or pulldown to avoid a floating GPIO input.
GPIO_03	D15	I/O	1	General purpose I/O 03 (hysteresis buffer). SPI1_CSZ0 (active low output): SPI1 chip select 0 signal. This pin is typically connected to the DLPAxxxx SPI_CSZ pin. Requires an external pullup resistor to deactivate this signal during reset and auto-initialization processes.
GPIO_02	D14	I/O	1	General purpose I/O 02 (hysteresis buffer). SPI1_DOUT (output): SPI1 data output signal. This pin is typicallyconnected to the DLPAxxxx SPI_DIN pin.
GPIO_01	C15	I/O	1	General purpose I/O 01 (hysteresis buffer). SPI1_CLK (output): SPI1 clock signal. This pin is typically connected to the DLPAxxxx SPI_CLK pin.
GPIO_00	C14	I/O	1	General purpose I/O 00 (hysteresis buffer). SPI1_DIN (input): SPI1 data input signal. This pin is typically connected to the DLPAxxxx SPI_DOUT pin.

(1) GPIO pins must be configured through software for input, output, bidirectional, or open-drain operation. Some GPIO pins have one or more alternative use modes, which are also software configurable. An external pullup resistor is required for each signal configured as open-drain.
(2) General purpose I/O for the DLPC1438 controller. These GPIO pins are software configurable.
(3) See Table 5-10 for type definitions.

Table 5-8. Clock and PLL Support

PIN		I/O	TYPE(1)	DESCRIPTION
NAME	NO.			
PLL_REFCLK_I	H1	I	11	Reference clock crystal input. If an external oscillator is used instead of a crystal, use this pin as the oscillator input.
PLL_REFCLK_O	J1	O	5	Reference clock crystal return. If an external oscillator is used instead of a crystal, leave this pin unconnected (floating with no added capacitive load).

(1) See Table 5-10 for type definitions.

Table 5-9. Power and Ground

PIN		I/O	TYPE	DESCRIPTION
NAME	NO.			
VDD	C5, D5, D7, D12, J4, J12, K3, L4, L12, M6, M9, D9, D13, F13, H13, L13, M10, D3, E3	—	PWR	Core 1.1-V power (main 1.1 V)
VDDLP12	C3	—	---	Unused. It is recommended to externally tie this pin to VDD.

ADVANCE INFORMATION

Table 5-9. Power and Ground (continued)

PIN		I/O	TYPE	DESCRIPTION
NAME	NO.			
VSS	C4, D6, D8, D10, E4, E13, F4, G4, G12, H4, H12, J3, J13, K4, K12, L3, M4, M5, M8, M12, G13, C6, C8, F6, F7, F8, F9, F10, G6, G7, G8, G9, G10, H6, H7, H8, H9, H10, J6, J7, J8, J9, J10, K6, K7, K8, K9, K10	—	GND	Core ground (eDRAM, DSI, I/O ground, thermal ground)
VCC18	C7, C9, D4, E12, F12, K13, M11	—	PWR	All 1.8-V I/O power: (1.8-V power supply for all I/O pins except the host or parallel interface and the SPI flash interface. This includes RESETZ, PARKZ, LED_SEL, CMP_OUT, GPIO, IIC1, TSTPT, and JTAG pins)
VCC_INTF	M3, M7, N3, N7	—	PWR	Host or parallel interface I/O power: 1.8 V to 3.3 V (Includes IIC0, PDATA, video syncs, and HOST_IRQ pins)
VCC_FLSH	D11	—	PWR	Flash interface I/O power: 1.8 V to 3.3 V (Dedicated SPI0 power pin)
VDD_PLLM	H2	—	PWR	MCG PLL (master clock generator phase lock loop) 1.1-V power
VSS_PLLM	G3	—	RTN	MCG PLL return
VDD_PLLD	J2	—	PWR	DCG PLL (DMD clock generator phase lock loop) 1.1-V power
VSS_PLLD	H3	—	RTN	DCG PLL return

Table 5-10. I/O Type Subscript Definition

I/O		SUPPLY REFERENCE	ESD STRUCTURE
SUBSCRIPT	DESCRIPTION		
1	1.8-V LVCMOS I/O buffer with 8-mA drive	V_{cc18}	ESD diode to GND and supply rail
2	1.8-V LVCMOS I/O buffer with 4-mA drive	V_{cc18}	ESD diode to GND and supply rail
3	1.8-V LVCMOS I/O buffer with 24-mA drive	V_{cc18}	ESD diode to GND and supply rail
4	1.8-V sub-LVDS output with 4-mA drive	V_{cc18}	ESD diode to GND and supply rail
5	1.8-V, 2.5-V, 3.3-V LVCMOS with 4-mA drive	V_{cc_INTF}	ESD diode to GND and supply rail
6	1.8-V LVCMOS input	V_{cc18}	ESD diode to GND and supply rail
7	1.8-V, 2.5-V, 3.3-V I^2C with 3-mA drive	V_{cc_INTF}	ESD diode to GND and supply rail
8	1.8-V I^2C with 3-mA drive	V_{cc18}	ESD diode to GND and supply rail
9	1.8-V, 2.5-V, 3.3-V LVCMOS with 8-mA drive	V_{cc_INTF}	ESD diode to GND and supply rail
10	Reserved		
11	1.8-V, 2.5-V, 3.3-V LVCMOS input	V_{cc_INTF}	ESD diode to GND and supply rail
12	1.8-V, 2.5-V, 3.3-V LVCMOS input	V_{cc_FLSH}	ESD diode to GND and supply rail
13	1.8-V, 2.5-V, 3.3-V LVCMOS with 8-mA drive	V_{cc_FLSH}	ESD diode to GND and supply rail

6 Device and Documentation Support

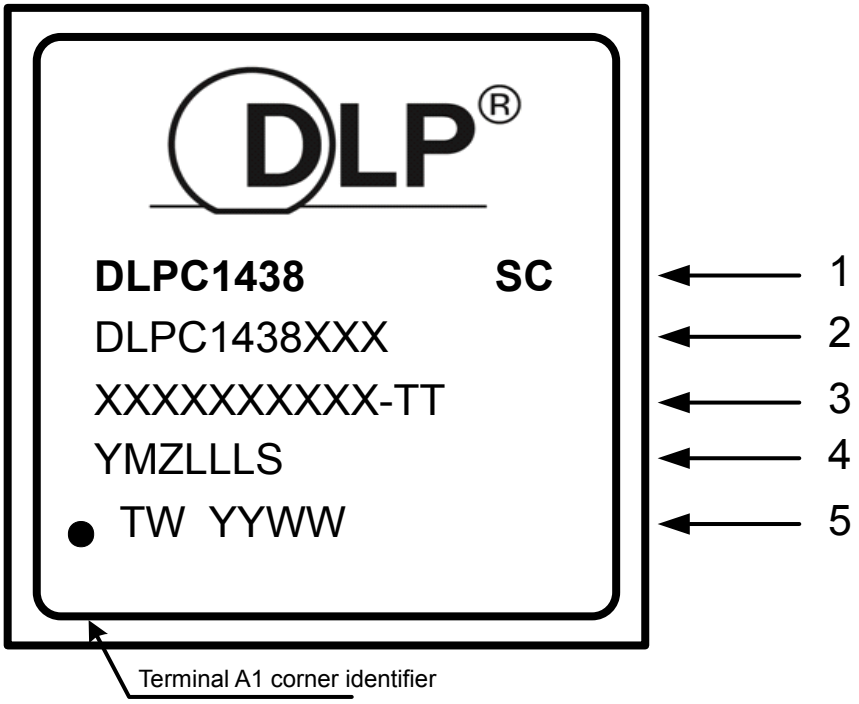
6.1 Device Support

6.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

6.1.2 Device Nomenclature

6.1.2.1 Device Markings



Marking Definitions:

Line 1:	DLP® Device Name: DLPC1438 device name ID. SC: Solder ball composition e1: Indicates lead-free solder balls consisting of SnAgCu G8: G indicates mold compound green; 8 indicates lead-free solder balls consisting of tin-silver-copper (SnAgCu) with silver content less than or equal to 1.5% and that the mold compound meets TI's definition of green.
Line 2:	TI Part Number DLP® Device Name: DLPC1438 = **x** indicates 8 device name ID. **XXX** corresponds to the device package designator.
Line 3:	XXXXXXXXXX-TT Manufacturer part number
Line 4:	Foundry lot code for semiconductor wafers and lead-free solder ball marking YM: Year month date code Z: Site code LLL: Assembly lot code S: Site code May also be in the format LLLLLL.ZZZ LLLLLL: Fab lot number ZZZ: Lot split number
Line 5:	PH YYWW: Package assembly information PH: Manufacturing site YYWW: Date code (YY = Year :: WW = Week)

ADVANCE INFORMATION

Note

1. Engineering prototype samples are marked with an **X** suffix appended to the TI part number. For example, 2512737-0001X.

6.2 Documentation Support

6.2.1 Related Documentation

The following table lists quick access links for associated parts of the DLP chipset.

Table 6-1. Chipset Documentation

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE
DLPA2000	Click here	Click here	Click here	Click here
DLPA2005	Click here	Click here	Click here	Click here
DLPA3000	Click here	Click here	Click here	Click here
DLPA3005	Click here	Click here	Click here	Click here
DLP300S	Click here	Click here	Click here	Click here
DLP301S	Click here	Click here	Click here	Click here

6.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

6.4 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

6.5 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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6.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

6.7 Glossary

TI Glossary — This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

For the device mechanical, packaging, and orderable information, refer to the Mechanical, Packaging, and Orderable Information section of the data sheet available in the DLPC1438 product folder.

ADVANCE INFORMATION

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
XDLPC1438ZEZ	ACTIVE	NFBGA	ZEZ	201	1	TBD	Call TI	Call TI	-30 to 105		Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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